

RELIABILITY DATA

LT1112 / LT1114

8/21/2006

• OPERATING LIFE TEST

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS ⁽¹⁾ AT +125°C	NUMBER OF ⁽²⁾ FAILURES
PLASTIC DIP	627	9422	9819	622.14	0
SOIC/SOT/MSOP	278	9736	0527	151.80	0
	905			773.94	0

• HIGHLY ACCELERATED STRESS TEST AT +131°C/85%RH

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS ⁽⁴⁾ AT +85°C	NUMBER OF FAILURES
PLASTIC DIP	137	9410	9705	186.62	0
	137			186.62	0

• PRESSURE COOKER TEST AT 15 PSIG, +121°C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS	NUMBER OF FAILURES
PLASTIC DIP	4,194	9245	0321	229.25	0
SOIC/SOT/MSOP	6,719	9248	0503	419.56	0
	10,913			648.81	0

• TEMP CYCLE FROM -65°C to +150°C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
PLASTIC DIP	746	9245	0321	223.56	0
SOIC/SOT/MSOP	1,944	9248	0503	748.00	0
	2,690			971.56	0

• THERMAL SHOCK FROM -65°C to +150°C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
PLASTIC DIP	204	9420	9545	118.19	0
SOIC/SOT/MSOP	1,284	9402	0402	343.17	0
	1,488			461.36	0

(1) Assumes Activation Energy = 1.0 Electron Volts

(2) Failure Rate Equivalent to +55°C, 60% Confidence Level = 2.38 FITS

(3) Mean Time Between Failures in Years = 47,932

(4) Assumes 20X Acceleration from 85°C to +131°C

Note: 1 FIT = 1 Failure in One Billion Hours.